

WHAT WE CLAIM IS:

1. A resin composition, comprising:

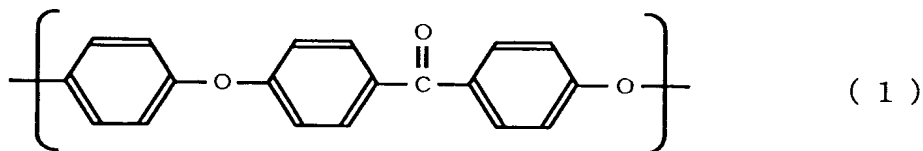
a resin component containing (A) 40 to 99% by mass of a poly(aryl ketone) and (B) 1 to 60% by mass of a

5 poly(arylene sulfide), and

(C) 0.1 to 5 parts by mass, per 100 parts by mass of said resin component, of at least one thermosetting imide resin selected from the group consisting of a polyfunctional unsaturated imide compound and a thermoset
10 product thereof.

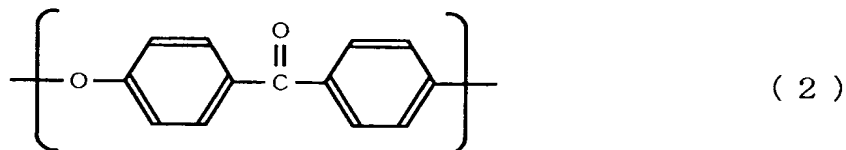
2. The resin composition according to claim 1, wherein said poly(aryl ketone) (A) is at least one poly(aryl ketone) selected from the group consisting of a poly(ether ether ketone) comprising a repeating unit
15 represented by the following formula (1) and a poly(ether ketone) comprising a repeating unit represented by the following formula (2):

Formula (1)



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Formula (2)



3. The resin composition according to claim 1, wherein said poly(arylene sulfide) (B) is a poly(arylene

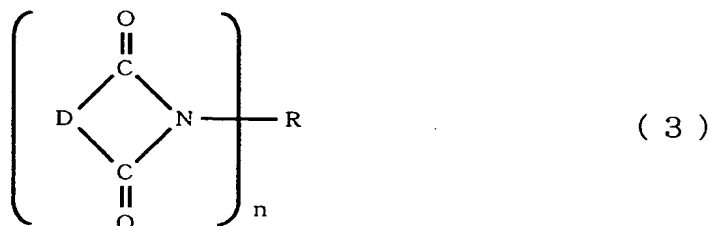
sulfide) having a melt viscosity of 10 to 1,000 Pa·s, as measured at a temperature of 310°C and a shear rate of 1,200/second.

4. The resin composition according to claim 1,
5 wherein said poly(arylene sulfide) (B) is a poly(phenylene sulfide).

5. The resin composition according to claim 1,
wherein said poly(arylene sulfide) has a pH of up to 8.0,
as measured in a mixed water/organic solvent solution
10 regulated to an acetone/water ratio of 1:2.

6. The resin composition according to claim 1,
wherein said thermosetting imide resin (C) is at least one
thermosetting imide resin selected from the group
consisting of a polyfunctional unsaturated imide compound
15 represented by the following formula (3) and a thermoset
product thereof:

Formula (3)



where D is a divalent organic group having a carbon-carbon
20 double bond, R is a di- or poly-valent organic group, and n
is an integer of 2 or greater.

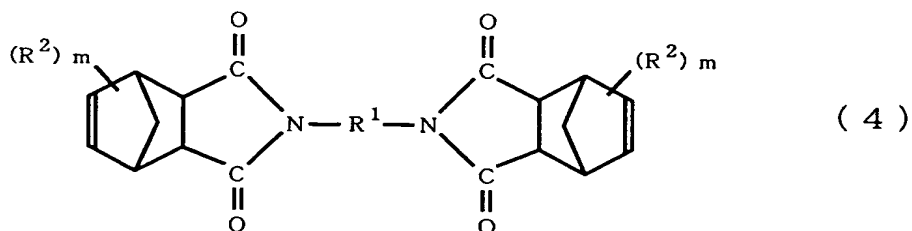
7. The resin composition according to claim 6,
wherein said polyfunctional unsaturated imide compound is a

polyfunctional nagiimide compound.

8. The resin composition according to claim 7, wherein said polyfunctional nagiimide compound is a bisnagiimide compound represented by the following formula

5 (4):

Formula (4)

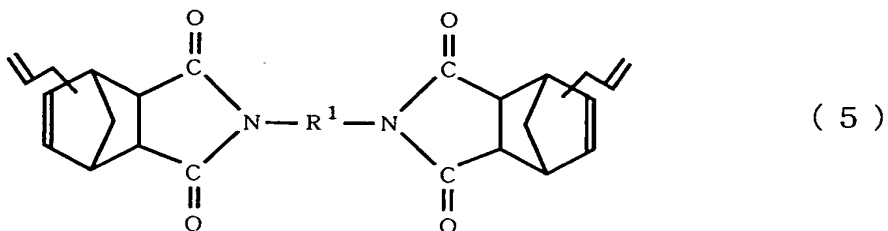


where R^1 is a divalent organic group, R^2 is a halogen atom, an alkyl group, an alkoxy group, an allyl group, an alkylidene group, an aryl group or an aralkyl group, and m is 0 or an integer of 1 to 6.

9. The resin composition according to claim 8, wherein said bisnagiimide compound is a bisallylnagiimide compound represented by the following formula (5):

15

Formula (5)



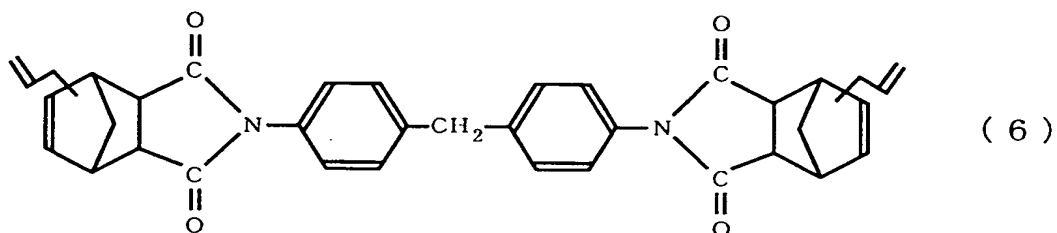
where R^1 is a divalent organic group.

10. The resin composition according to claim 9, wherein said bisallylnagiimide compound is a compound

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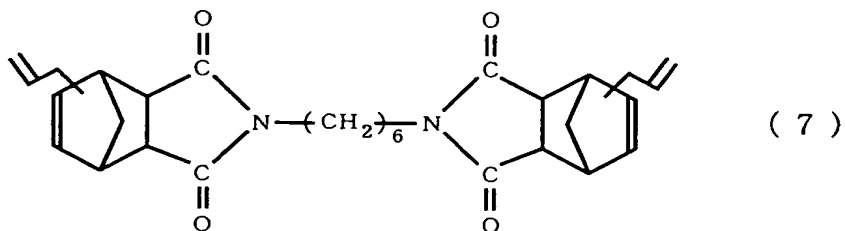
represented by the following formula (6):

Formula (6)



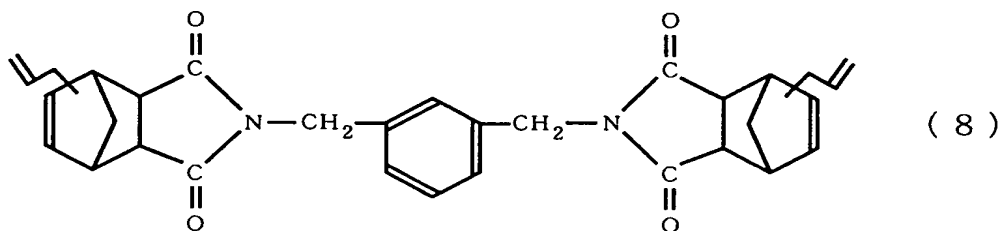
11. The resin composition according to claim 9,
5 wherein said bisallylnagiimide compound is a compound
represented by the following formula (7):

Formula (7)



12. The resin composition according to claim 9,
10 wherein said bisallylnagiimide compound is a compound
represented by the following formula (8):

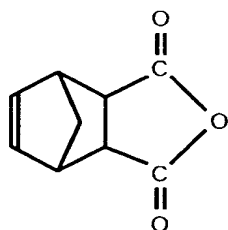
Formula (8)



13. The resin composition according to claim 9,
15 wherein said bisallylnagiimide compound has been
synthesized by allowing nadic anhydride represented by the

following formula (9) or a monoalkyl ester of nadic acid to react with a diamine, followed by a dehydration ring-closure reaction:

Formula (9)



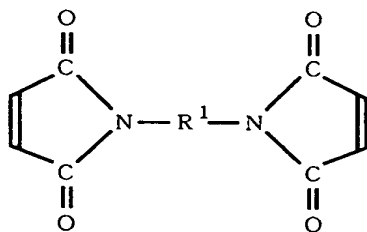
(9)

5

14. The resin composition according to claim 6, wherein said polyfunctional unsaturated imide compound is a bismaleimide compound represented by the following formula (10):

10

Formula (10)



(1 0)

where R^1 is a divalent organic group.

15. The resin composition according to claim 1, wherein said thermosetting imide resin (C) is a polyfunctional unsaturated imide compound prior to thermosetting.

16. The resin composition according to claim 1, wherein said thermosetting imide resin (C) is a thermoset product of a polyfunctional unsaturated imide compound.

20 17. The resin composition according to claim 16, wherein said thermoset product is obtained by heating said

polyfunctional unsaturated imide compound at a temperature of 200 to 300°C for 30 minutes to 72 hours for thermosetting.

18. The resin composition according to claim 16,
5 wherein said thermoset product is a thermoset product of a bisallylnagiimide compound.

19. The resin composition according to claim 1,
which further contains a filler in an amount of up to 800
parts by mass per 100 parts by mass of said resin component.

10 20. The resin composition according to claim 19,
wherein said filler is a fibrous filler.